

> Features

- Size 0.34*0.25 inch
- RoHS compliant, lead-free and halogen-free
- Fast response to fault current
- Low profile
- High voltage
- Compatible with high temperature solders

> Applications

- Computer, Mobile phones, Multimedia
- Automotive, Industrial controls, Telephony and broadband
- Game machines, Portable electronics, Battery

> Electrical Characteristics (25°C)

Part Number	I _{hold}	Itrip	V _{max}	I _{max}	P _{d typ}	Time to trip		R _{min}	R1 _{max}
Part Number	(A)	(A)	(V _{dc})	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)
BSMD3425-200-60V	2.00	4.00	60	20	2.5	8.00	10.0	0.040	0.200
BSMD3425-260-60V	2.60	5.20	60	20	2.5	8.00	10.0	0.020	0.120
BSMD3425-300-36V	3.00	6.00	36	20	2.5	8.00	20.0	0.010	0.060



> Vocabulary

- **I**hold = Hold current: maximum current device will pass without tripping in 25°C still air.
- **I**trip = Trip current: minimum current at which the device will trip in 25°C still air.
- V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max}).
- I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max}).
- $P_{d typ.}$ = Typical power dissipated from device when in the tripped state at 25°C still air.
- **R**_{min} = Minimum resistance of device in initial (un-soldered) state.
- **R**_{1max} = Maximum resistance of device at 25°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

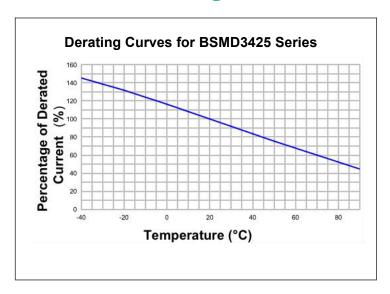
Caution: Operation beyond the specified ratings may result in damage and possible arcing and flame.

Warning

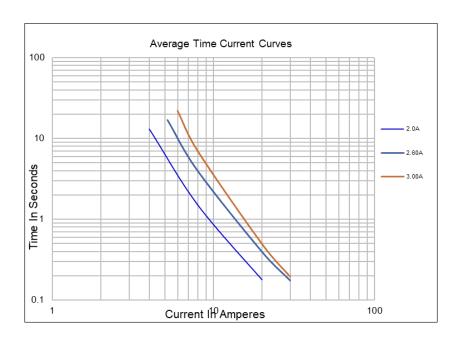
- Users shall independently assess the suitability of these devices for each of their applications.
- Operation of these devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire.
- These devices are intended to protect against the effects of temporary over-current or over-temperature conditions and are not intended to perform as protective devices where such conditions are expected to be repetitive or prolonged in duration.
- Exposure to silicon-based oils, solvents, electrolytes, acids, and similar materials can adversely affect the prolonged of these PPTC devices.
- These devices undergo thermal expansion under fault conditions, and thus shall be provided with adequate space and be protected against mechanical stresses.
- Circuits with inductance may generate a voltage (L di/dt) above the rated voltage of the PPTC device.



> Thermal Derating Curve



> Average Time-Current Curve





> Thermal Derating Chart

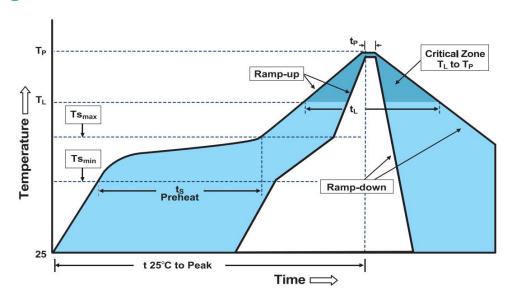
Part Number	Ambient operating temperature hold current(Ihold)										
Part Number	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C		
BSMD3425-200-60V	3.07	2.73	2.39	2.00	1.71	1.54	1.37	1.20	0.95		
BSMD3425-260-60V	4.01	3.56	3.12	2.60	2.22	2.00	1.77	1.55	1.21		
BSMD3425-300-36V	4.43	3.98	3.52	3.00	2.61	2.39	2.16	1.93	1.59		

> **Environmental Specifications**

Test	Conditions	Resistance change				
Passive aging	+85°C, 1000 hours	±5% typical				
Humidity aging	+85°C, 85% R.H., 168 hours	±5% typical				
Thermal shock	+85°C to -40°C, 20 times	±33% typical				
Resistance to solvent	MIL-STD-202,Method 215	No change				
Vibration	MIL-STD-202,Method 201 No change					
Ambient operating conditions : - 40 °C to +85 °C						
Maximum surface temperature of the device in the tripped state is 125 °C						



> Soldering Parameters



Profile Feature	Pb-Free Assembly				
Average Ramp-Up Rate(Ts _{max} to T _p)	3°C/second max				
Preheat					
-Temperature Min(Ts _{min})	150°C				
-Temperature Max(Ts _{max})	200°C				
-Time(Ts _{min} to Ts _{max})	60~180 seconds				
Time maintained above:					
-Temperature(T _L)	217°C				
-Time(t _L)	60~150 seconds				
Peak Temperature(T _p)	260°C				
Ramp-Down Rate	6°C/second max				
Time 25°C to Peak Temperature	8 minutes max				
Storage Condition	0°C~30°C,30%-60%RH				

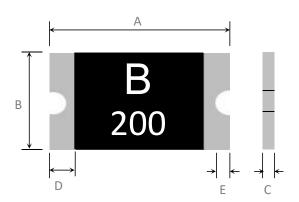
- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead-free.
- Recommended maximum paste thickness is 0.25mm.
- Devices can be cleaned using standard industry methods and solvents.

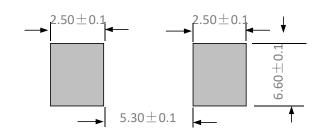
Note 1: All temperature refer to topside of the package, measured on the package body surface.

Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.



> Physical Dimensions & Recommended Pad Layout (mm)

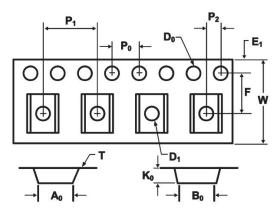




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Part Number	Marking	Quantity	Min	Max	Min	Max	Min	Max	Min	Min
BSMD3425-200-60V	B200	1500	8.30	9.00	6.00	6.70	1.00	2.00	0.30	0.25
BSMD3425-260-60V	B260	1500	8.30	9.00	6.00	6.70	1.00	2.00	0.30	0.25
BSMD3425-300-36V	B300	1500	8.30	9.00	6.00	6.70	1.00	2.00	0.30	0.25

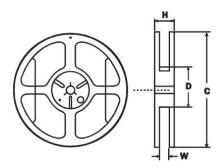


> Tape And Reel Specifications (mm)



Governing Specifications	BSMD3425-200-60V BSMD3425-260-60V BSMD3425-300-36V					
W	16.0 ± 0.3					
F	7.5 ± 0.05					
E ₁	1.75 ± 0.1					
D_0	1.50 ± 0.05					
D_1	1.55 _{min}					
P ₀	4.0 ± 0.1					
P ₁	8.0 ± 0.1					
P ₂	2.0 ± 0.05					
A ₀	7.0 ± 0.1					
B ₀	9.5 ± 0.1					
Т	0.6					
K ₀	2.2					
Leader _{min}	390					
Trailer _{min}	160					

Reel Dimensions					
С	$\phi 180 \pm 3.0$				
D	$\phi 60.2 \pm 0.5$				
Н	22.4 ± 1.0				
W	16.4 ± 0.2				



> Contact information

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